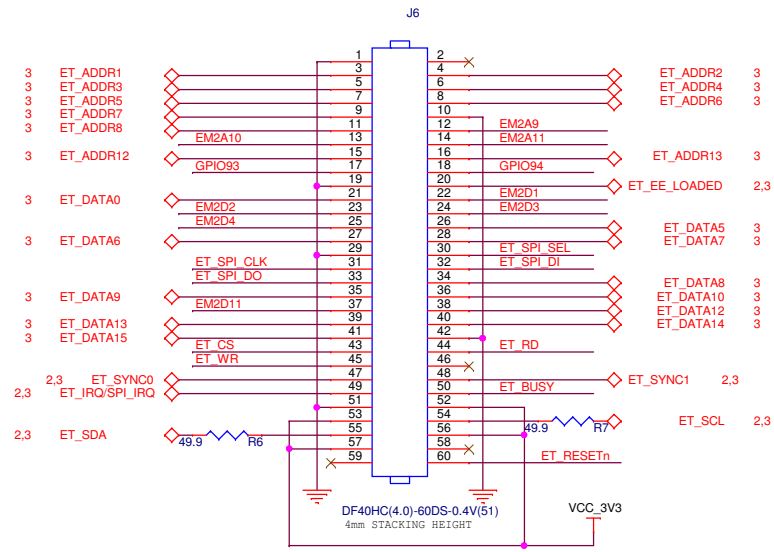


MH1 MH2 MH3
○ ○ ○
NP NP NP

J3 DEFAULT JUMPER POP 1-2
J10 DEFAULT JUMPER POP 1-2

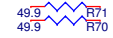
TEXAS INSTRUMENTS		
Title: BOOSTXL-ETHERCAT		
Page Contents: TITLE		
Size: C	DOC NO: MCU006	REV: A
Date: Wednesday, August 24, 2016	Sheet 1	of 5

CONTROL CARD SPI/EMIF CONNECTIONS

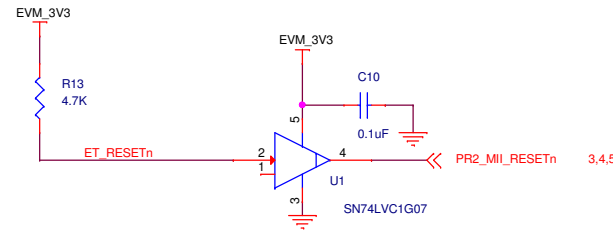
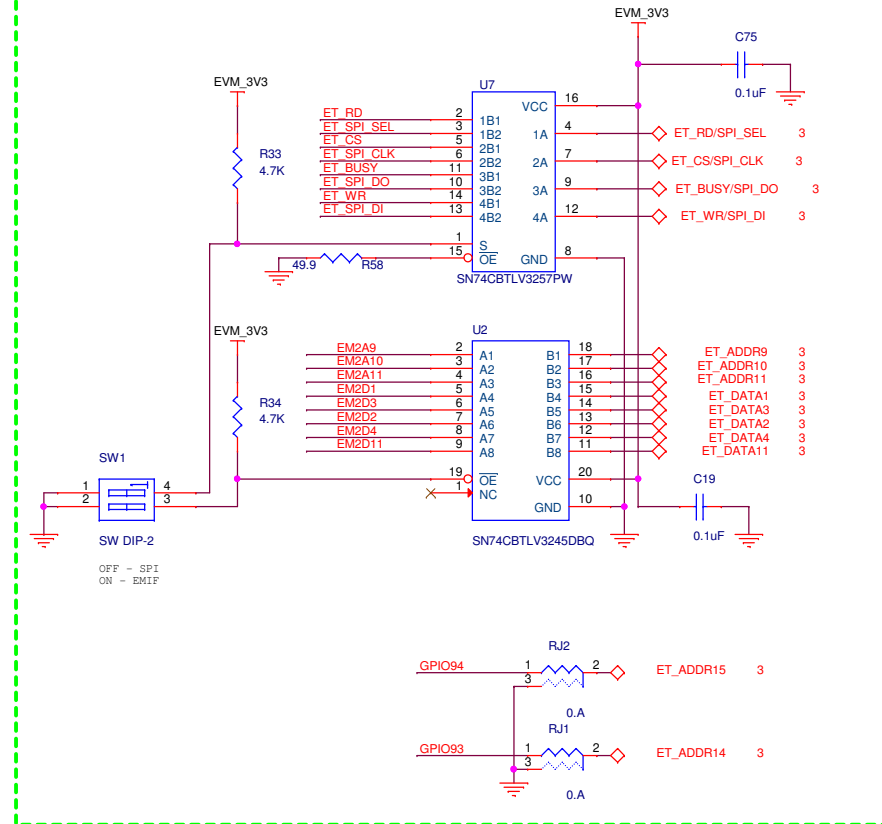


LAUNCH PAD CONNECTIONS

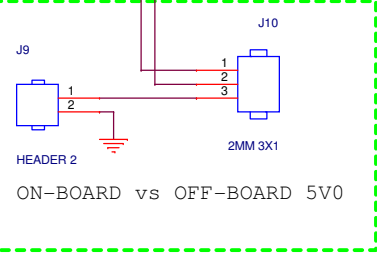
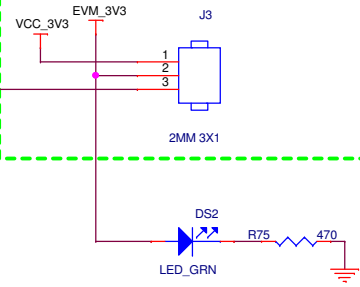
R70/R71 REMAIN TO PRESERVE
SOLDER PASTE STENCIL.



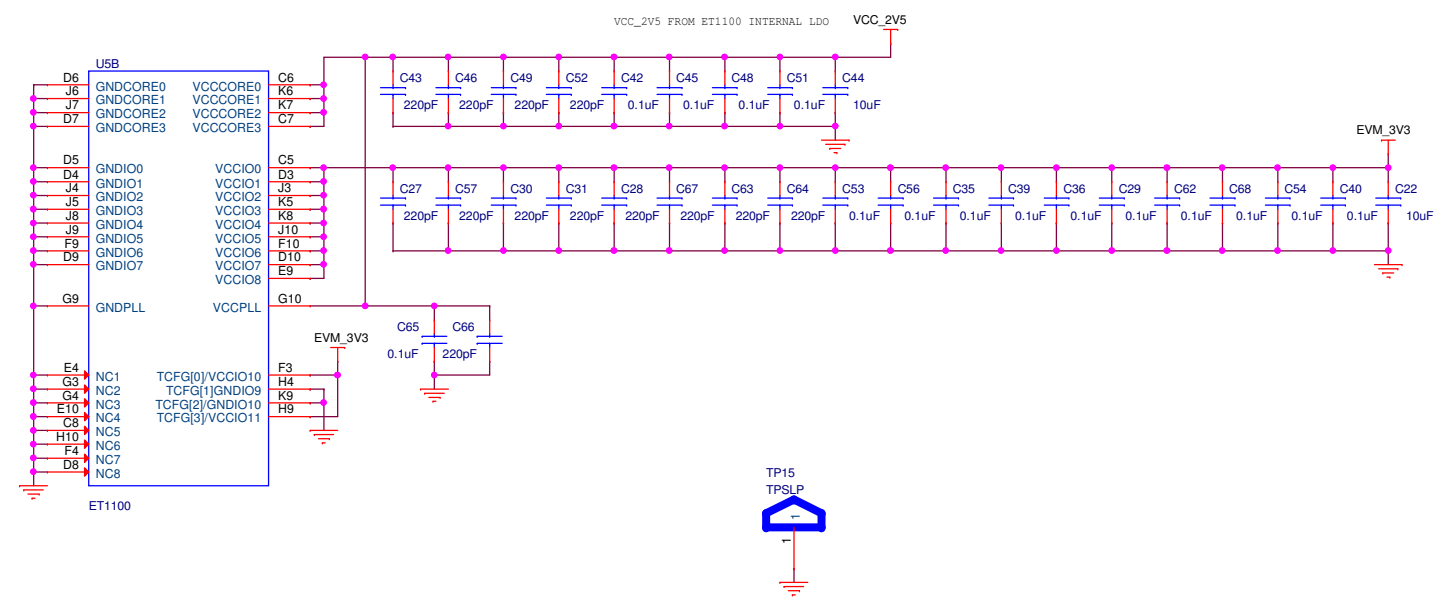
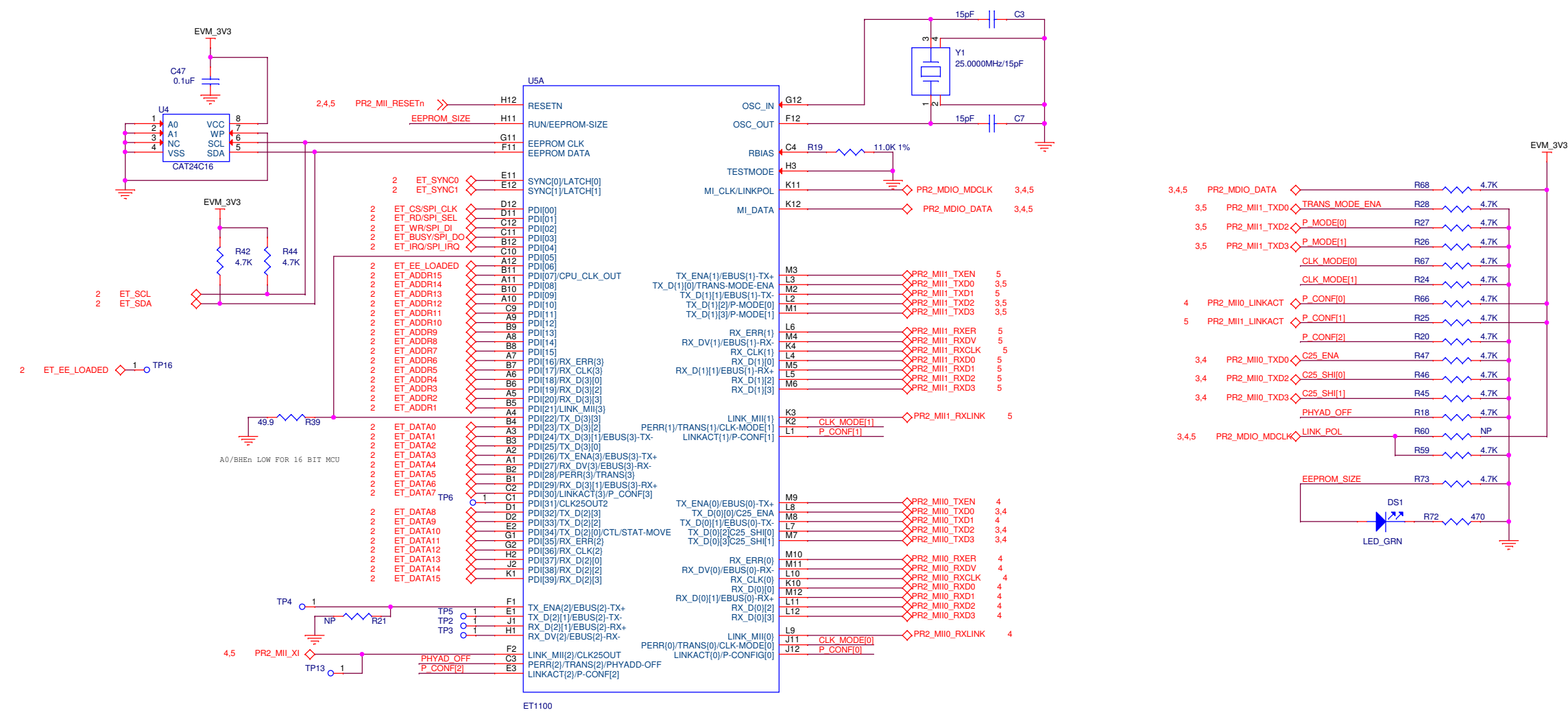
SPI vs EMIF POPULATIONS



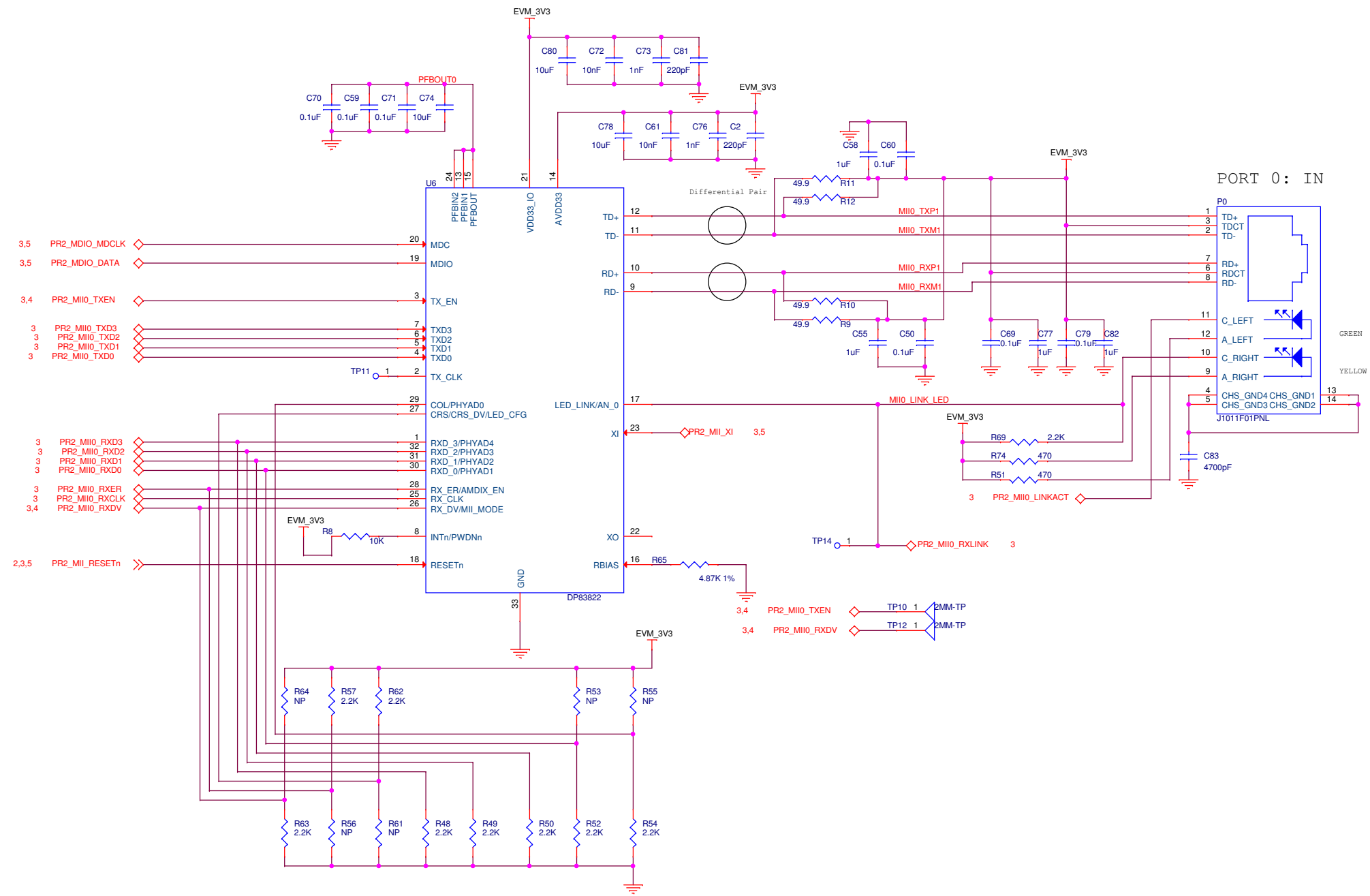
ON-BOARD vs OFF-BOARD 3V3



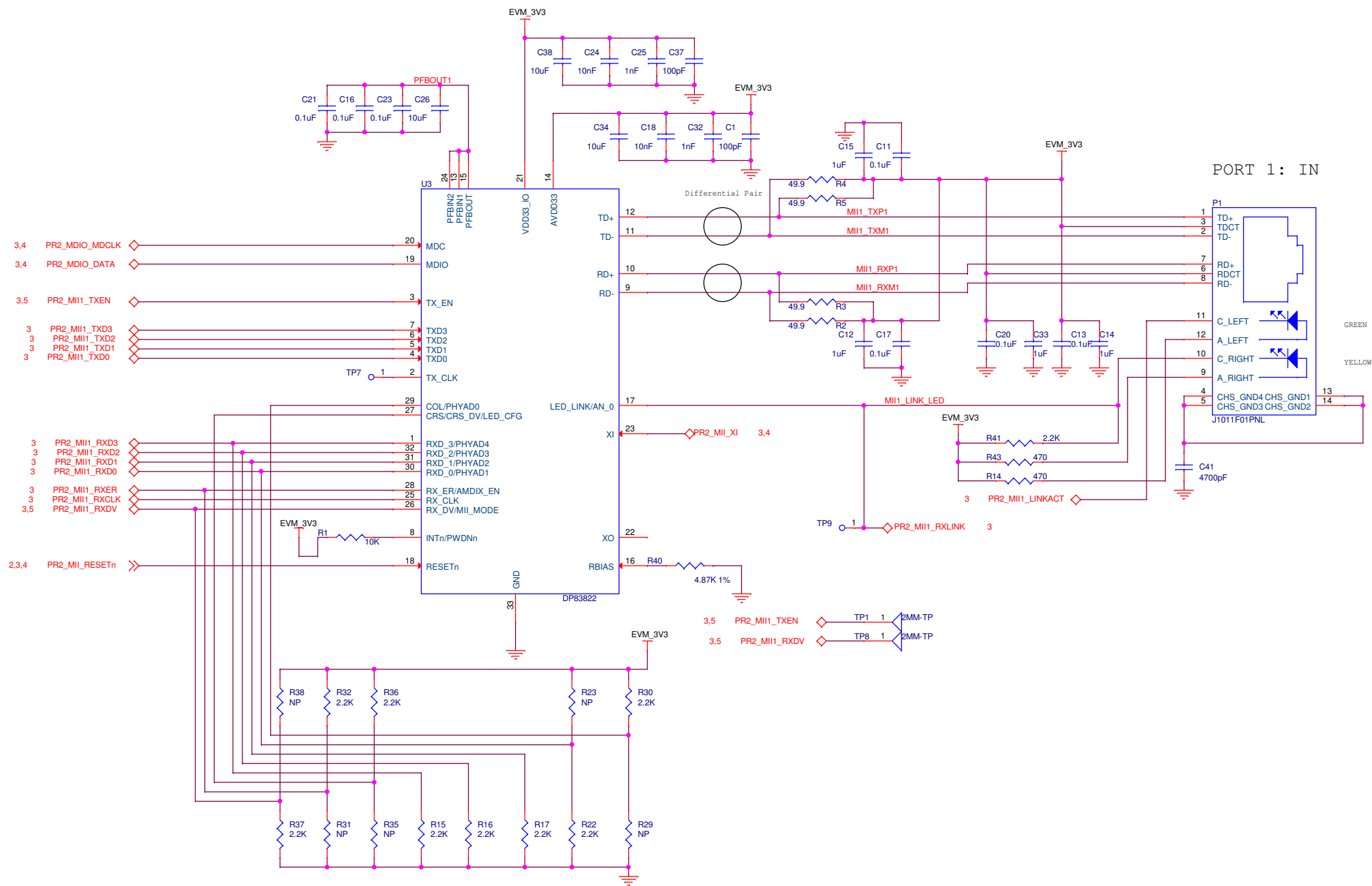
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Page Contents: TITLE		
Size: C	DOC NO: MCU006	REV: A
Date: Wednesday, August 24, 2016	Sheet 2	of 5



TEXAS INSTRUMENTS			
Title: BOOSTXL-ETHERCAT			
Page Contents: TITLE			
Size: C	DOC NO: MCU006	REV: A	
Date: Wednesday, August 24, 2016	Sheet 3	of	5



TEXAS INSTRUMENTS		
Title: BOOSTXL-ETHERCAT		
Page Contents: TITLE		
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Date: Wednesday, August 24, 2016	Sheet 4	of 5



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